



# SOT141-8

plastic DIL-bent-SIL power package; 13 leads (lead length 7.7 mm)

25 September 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	Z (zig-zag)
<b>Package type descriptive code</b>	DBS13P
<b>Package type industry code</b>	DBS13P
<b>Package style descriptive code</b>	DBS (DIL-bent-SIL)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	12-03-2003
<b>Manufacturer package code</b>	SOT141

**Table 1. Package summary**

<b>Parameter</b>	<b>Min</b>	<b>Nom</b>	<b>Max</b>	<b>Unit</b>
package length	23.6	23.7	24	mm
package width	11.8	12	12.2	mm
seated height	15.5	17	17	mm
package height	4.4	4.4	4.6	mm
nominal pitch	-	1.7	-	mm
actual quantity of termination	-	13	-	



2 Package outline

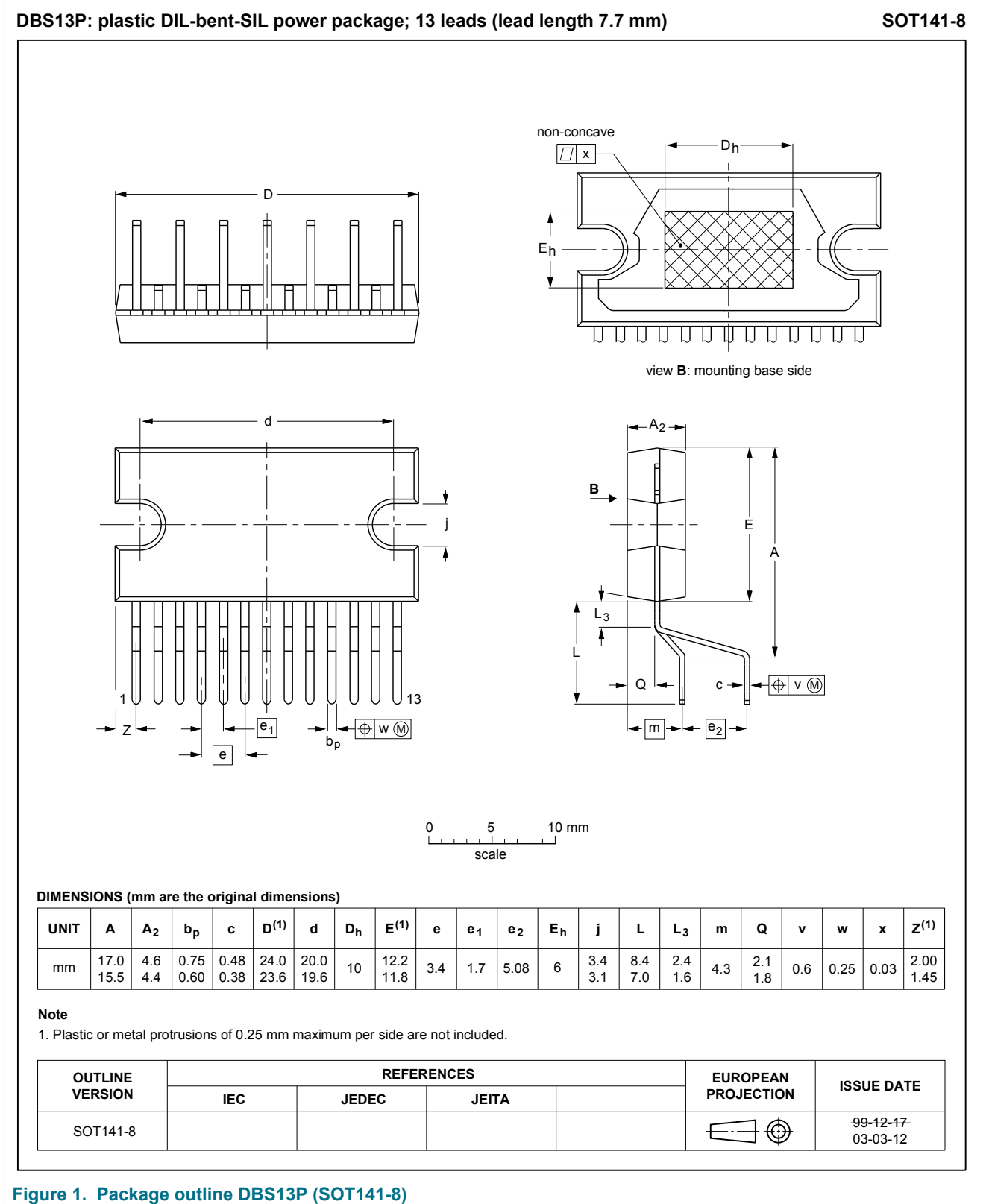


Figure 1. Package outline DBS13P (SOT141-8)

### 3 Legal information

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